

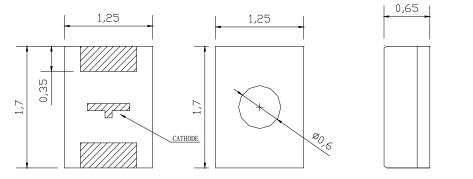
Features

- Low Power Consumption
- Various Colors
- Meet ROHS Green Product.

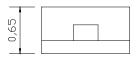
Applications

• Backlight and Indicator

Package Dimensions







Patent Protection

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.2 mm(.0079") unless otherwise noted.
- 3. Specifications are subject to change without notice
- 4. This drawing is only for reference, not as a basis for the actual structure.

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Rev : V.2 Prepared By:



Selection Guide

Part No	Lens Type	Dice	Emitted Color
FDC-T165R-6T5NTDF	Black	AllnGap	Red

Electrical / Optical Characteristics At Ta=25 °C

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Condition
Iv	Luminous Intensity(Note 1)	11.2	45	72.0	mcd	IF=5mA
入 Peak	Peak Emission Wavelength		632		nm	IF=5mA
入d	Dominant Wavelength		631		nm	IF=5mA
$ riangle \lambda$	Spectral Line Half-Width		20		nm	IF=5mA
VF	Forward Voltage		2.0	2.5	V	IF=5mA
IR	Reverse Current			10	μA	VR=5V

Note:

1. The Luminous Intensity is measured with the led excluded the black lens cover.

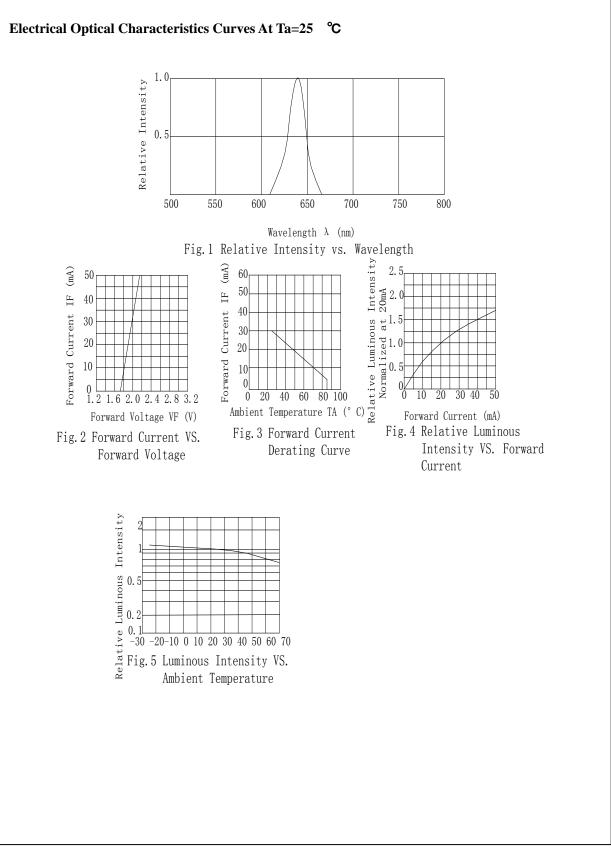
Absolute Maximum Ratings At Ta=25℃

Parameter	Red	Unit	
Power Dissipation	75	mW	
Peak Forward Current[1]	80	mA	
Continuous Forward Current	30	mA	
Dreading Linear From25℃	0.4	mA/°C	
Reverse Voltage	5	V	
Electrostatic Discharge Threshold(HBM)	2000 V		
Operating Temperature Range	-55°C to + 85°C		
Storage Temperature Range	-55℃ to + 85℃		
Soldering Condition	260 ℃ For 5 Seconds		

Note:

1. 1/10DutyCycle, 0.1msPulseWidth







Bin Range Of Luminous Intensity

0	ť				
Symbol	Bin Code	Min.	Max.	Unit	Condition
	L	11.2	18.0		
T	М	18.0	28.0	mcd	IF=5mA
Iv	Ν	28.0	45.0		
	Р	45.0	72.0		

Bin Range Of Forward Voltage

Symbol	Bin Code	Min.	Max.	Unit	Condition
	V2	1.7	1.9	v	I=5mA
VE	V3	1.9	2.1		
VF	V4	2.1	2.3		
	V5	2.3	2.5		

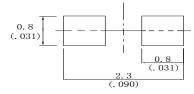
Notes:



Process Note

- 1. Sells gives no other assurances regarding the ability of to withstand ESD. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.
- 2. Reflow soldering should not be done more than two times.
- 3. Do not stress LED when soldering, and do not warp the circuit board after soldering
- 4. While using Iron, Power dissipation of Iron should be smaller than 25W, and temperature should be controllable. The work should be finished within 2 sec under 320°C for once only.

Recommended Soldering Pad Dimensions



Notes:

- 1. The LEDs should be used within a year.
- 2. The LEDs should be kept in $5 \sim 30^{\circ}$ C and 60° RH for less.
- 3. The LEDs should be used within 24 hours, or else should be kept a 5~30°C and 30% RH or less. And LEDs should be used within 7 days after opening the package.



Reliability Test Items Conditions

FDC-T165R-6T5NTDF

Classification	Test Item	Test Conditions	Test hours	Result
Endurance Test	Operation Life	Connect with a power IF=5mA Ta=Under room temperature	1000Hrs	0/20
	High Temperature High Humidity	Ta=+65°C±5°C RH=90%-95%	240Hrs	0/20
	High Temperature Storage	High Ta=+85℃±5℃	1000Hrs	0/20
	Low Temperature Storage	Low Ta=-35°C±5°C Test time=1000hrs	1000Hrs	0/20
	Temperature Cycling	-45℃~+105℃ 15min 5min 15min	300 Cycles	0/20
Environmental Test	Thermal Shock	-35°C∼±5°C∼+85°C∼±5°C 5min 10sec 5min	300 Cycles	0/20
	Solder Resistance	Preheating: 120°C-150°C, within 2 minutes. Operation heating : 260°C (Max.), within 5 seconds (Max.)	5Cycles	0/20

Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	VF(V)	IF=5mA	Over U×1.2
Reverse current	Ir(µA)	Vr=5V	Over U×2
Luminous intensity	Iv(mcd)	IF=5mA	Below S×0.5

Note: 1.U means the upper limit of specified characteristics. S means initial value.

2.Meansurment shall be taken between 2 hours after the test pieces have been returned to normal ambient conditions after completion of each test.